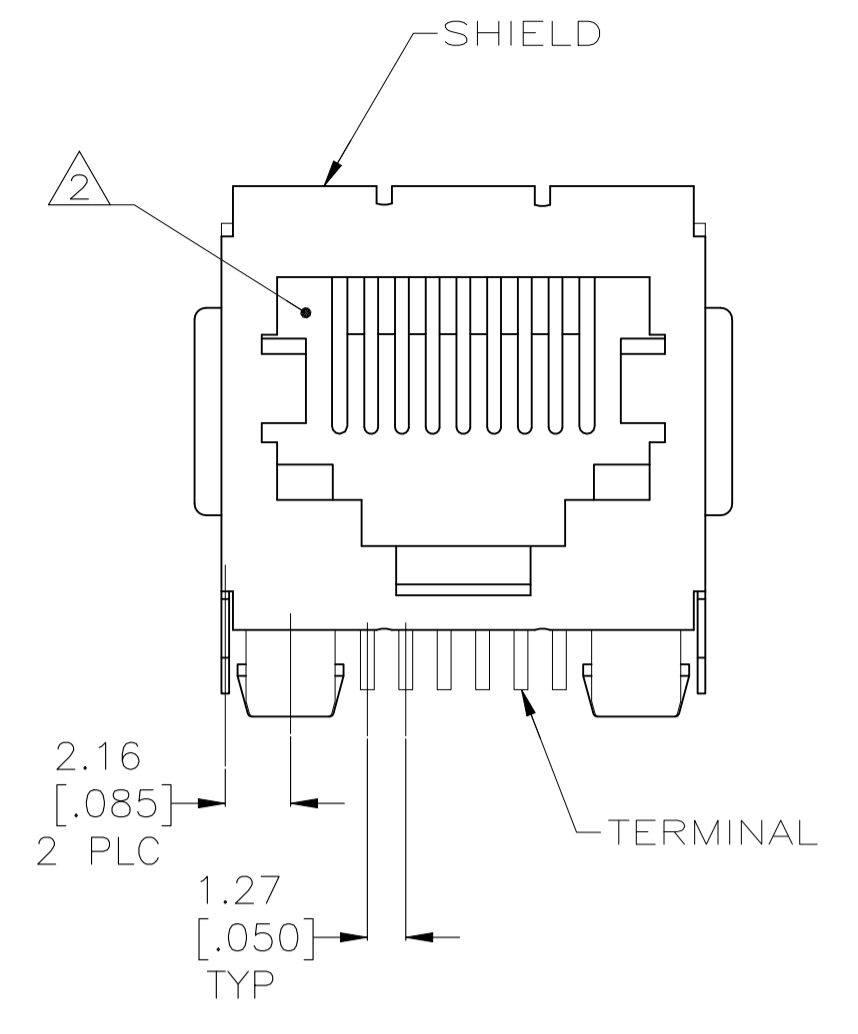
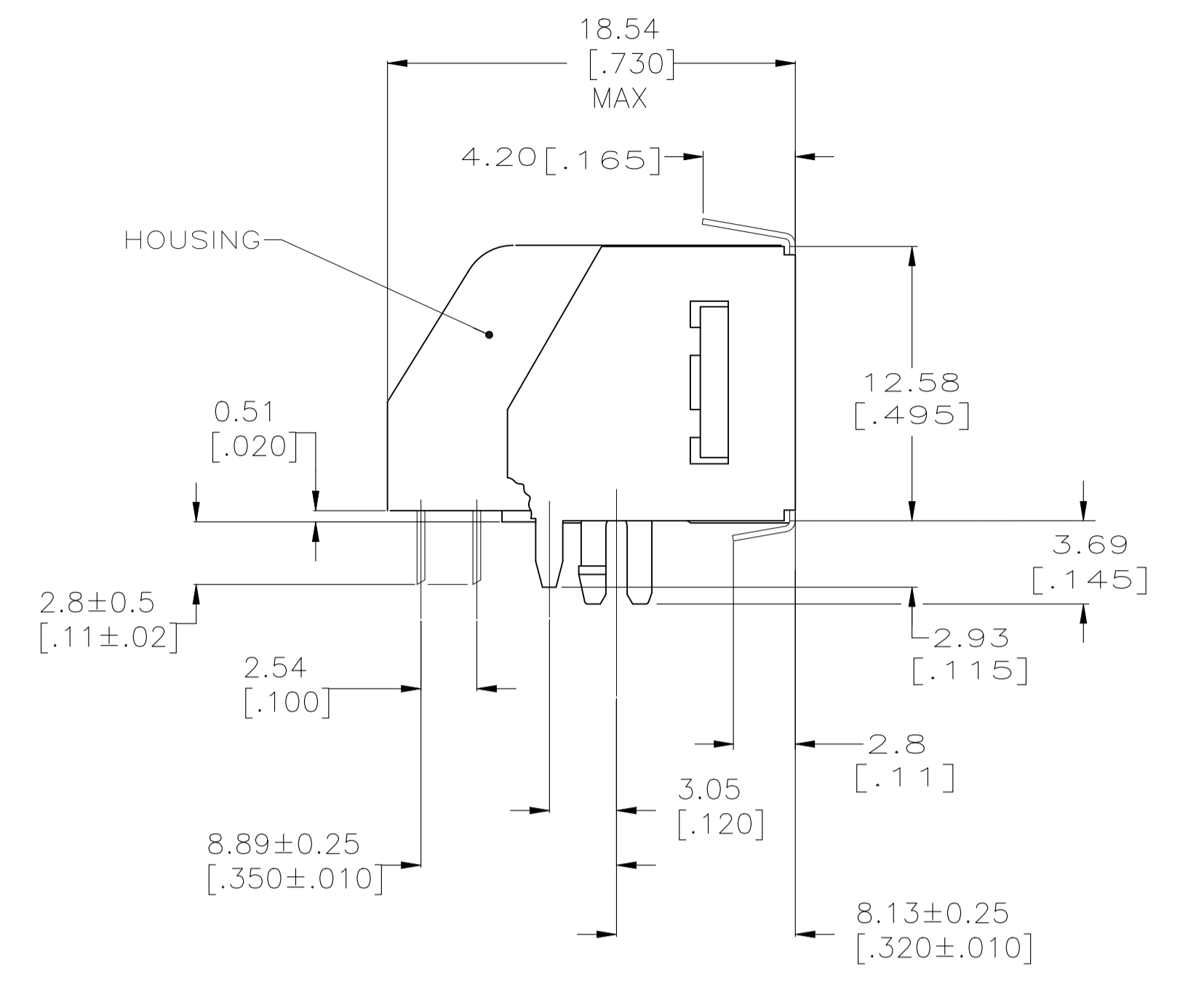
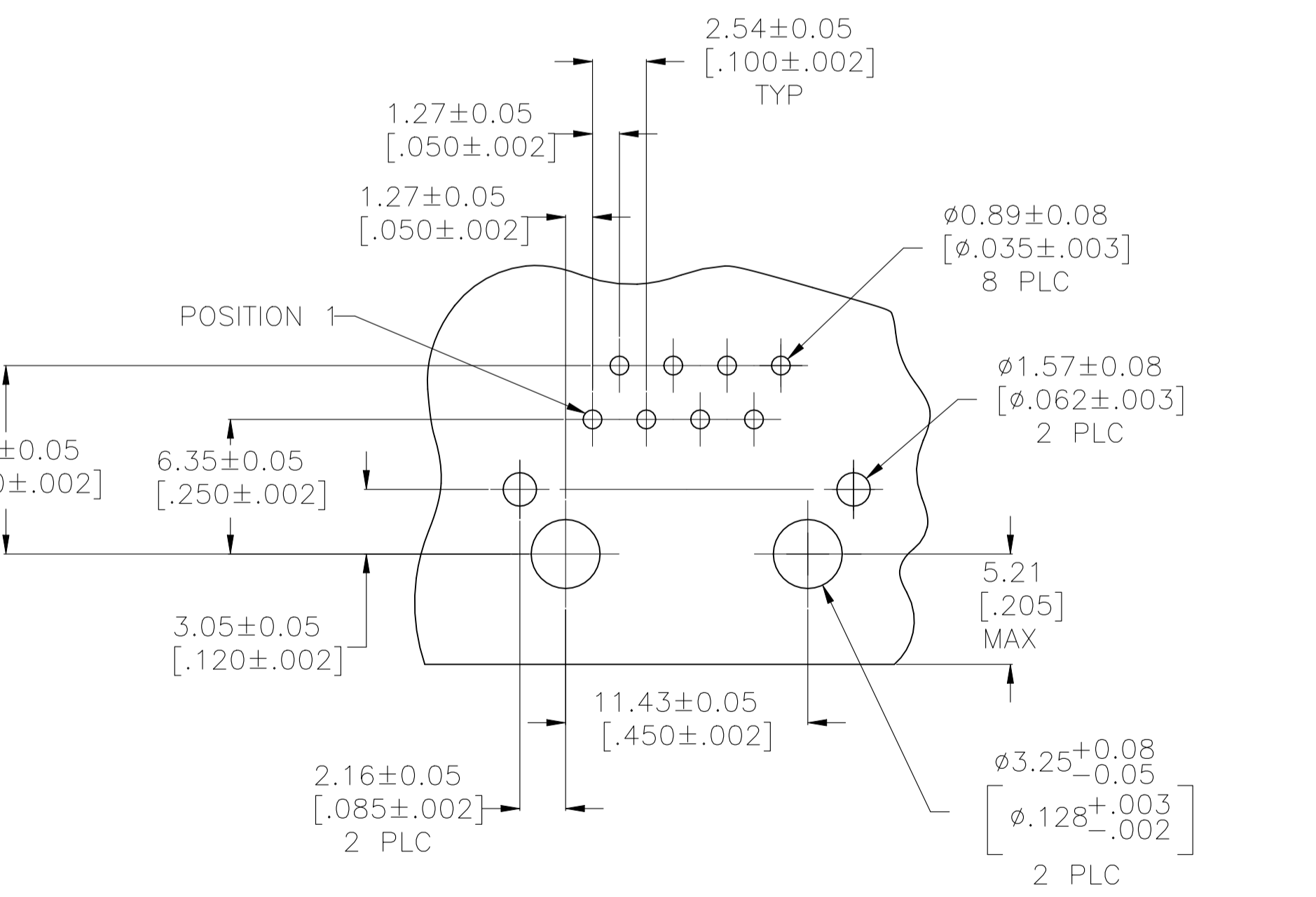
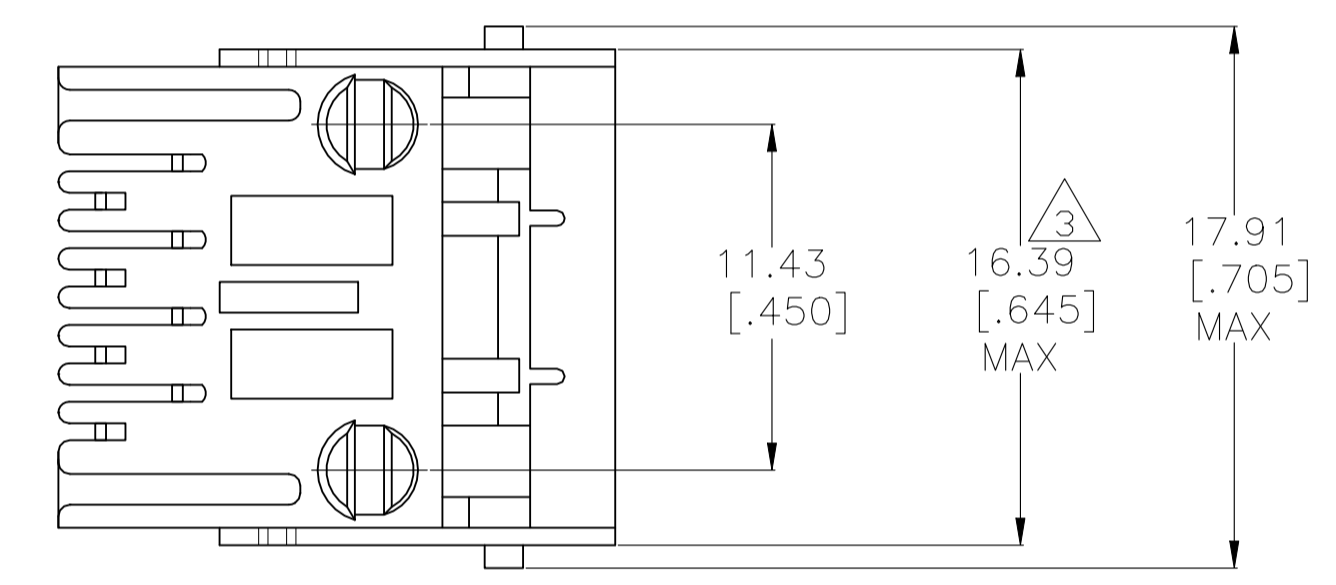


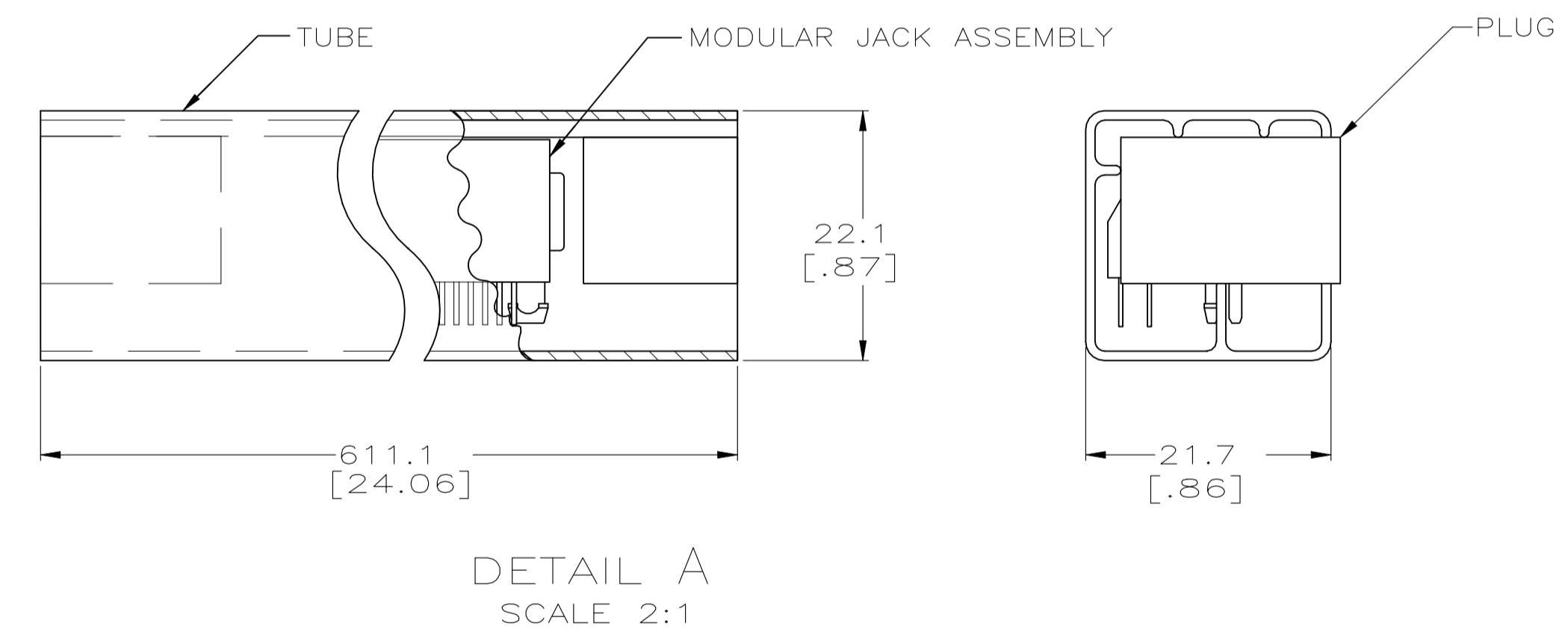
REVISIONS					
REV	DESCRIPTION	DATE	BY	CHK	APPV
B1	REVISED PER ECN-22-180673	20OCT2022	AK	SZ	



- MATERIAL:
HOUSING - HTN MOLDING COMPOUND, UL 94V-0, BLACK
TERMINAL - 0.36[.014] THICK PHOS-BRONZE
PLATED WITH 1.27µm[.000050] MINIMUM THICK HARD
GOLD IN LOCALIZED GOLD PLATE AREA AND
3.81µm[.000150] MINIMUM THICK MATTE TIN IN
SOLDER AREA OVER 1.27µm[.000050] THICK MINIMUM
NICKEL UNDERPLATE.
SHIELD - 0.25[.010] THICK COPPER ALLOY PLATED
WITH 3.0µm[.000120] MINIMUM REFLOWED TIN
- CAVITY CONFORMS TO FCC RULES AND REGULATIONS PART 68, SUBPART F.
- DIMENSION MEASURED ALONG FRONT EDGE OF MATING FACE
- PACKAGED 31 ASSEMBLIES PER TUBE WITH BOTH ENDS PLUGGED (SEE DETAIL A)



RECOMMENDED PRINTED CIRCUIT BOARD LAYOUT
(COMPONENT SIDE)



OBSOLETE 6368018-1
PART NUMBER

THIS DRAWING IS A CONTROLLED DOCUMENT.		DIN 15JUN2005 L. VARELA - DOCKS		TE Connectivity	
DIMENSIONS: mm [INCHES]		TOLERANCES UNLESS OTHERWISE SPECIFIED: 0 PLC ± - 1 PLC ± - 2 PLC ± 0.13[.005] 3 PLC ± - 4 PLC ± - ANGLES ± -		APVD 15JUN2005 S. FLICKINGER	
MATERIAL SEE NOTE 1		FINISH SEE NOTE 1		WEIGHT 0.000000	
CUSTOMER DRAWING		SCALE 4:1		SHEET 1 of 1 REV B1	